### Overview

### **HP Elite Dragonfly G2 Notebook PC**



#### Left

- 1. Internal Microphones
- 2. IR Camera LEDs
- 3. Webcam and IR Camera
- 4. Privacy Camera Shutter
- 5. Webcam LED

- 6. Glass Clickpad
- 7. WWAN SIM (Nano) 1
- 8. Nano Security Lock Slot (Lock sold separately)
- 9. Power Button
- 10. SuperSpeed USB Type-A 5Gbps signaling rate (Charging port)
- 1. All units have a SIM card slot and icon but units that do not support WWAN are shipped with a non-removable SIM slot plug.

### Overview



- 1. HDMI 2.0 port (Cable not included)
- 2. Audio Combo Jack
- 3. Thunderbolt<sup>™</sup> 4 with USB4 Type-C<sup>®</sup> 40Gbps signaling rate (USB Power Delivery, DisplayPort<sup>™</sup> 1.4)<sup>1</sup>
- Right
- Thunderbolt™ 4 with USB4 Type-C® 40Gbps signaling rate (USB Power Delivery, DisplayPort™ 1.4)¹
- 5. Touch Fingerprint Sensor
- 1. SuperSpeed USB 20Gbps is not available with Thunderbolt™ 4.

#### Overview

#### AT A GLANCE

- Precision Machined CNC Mg Unibody with Narrow borders, a chassis that is .63 inches (1.61 cm) thin and with a starting weight of 2.18 lbs. (<1 Kg)</li>
- A 360° convertible notebook with 4 usage modes: Laptop mode, Tablet mode, Tent mode, and Media mode
- Integrated HP Privacy Camera, with HP Sure Shutter to protect from malicious surveillance
- Choice of 11th Generation Intel<sup>®</sup> Core<sup>™</sup> i7, i5 and i3 processors
- Intel® EVO configurations available
- Intel® Core™ i5 and i7 feature integrated Intel® Iris® Xe Graphics
- Touch display choices include 33.78 cm (13.3") diagonal IPS FHD displays or stunning UHD HDR-400 display. Brightness
  choices up to 1000 Nits. Get added protection in open or public places with the optional HP Sure View Reflect integrated
  privacy screen
- Ultimate connectivity with dual Thunderbolt4 Type-C<sup>®</sup> with USB4 support ports, dual USB 3.1 Gen1 charging ports, and HDMI 2.0
- Stay connected where you need to with a choice of 5G or 4G/LTE WWAN, WLAN and optional Thunderbolt™ Docking (Sold separately)
- Never forget your password with your choice of simple authentication methods, including the IR camera for face recognition and Touch Fingerprint Sensor for Windows Hello
- LPDDR4X Memory up to 32 GB supports dual channel performance
- Up to 16 hours 30 minutes of battery life (56 Wh battery) and up to 11 hours of battery life (38 Wh battery)
- Preinstalled with Windows 10 versions or FreeDOS
- Passed 19 MIL-STD 810H tests <sup>1</sup>
- Instant on/instant off with Modern Connected Standby
- Al based HP Context Aware to maximize performance when working at a table, comfort when working from your lap, and responsiveness when working on the go
- HP Dynamic Audio, a new AI-based audio experience, tunes output to speech, music, and movies all while suppressing background noise (Planned to be available March 2021.)
- HP Sound Calibration to uniquely tune end user headphone audio (Planned to be available March 2021.)

1. MIL-STD 810H is not intended to demonstrate fitness of U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



### **Technical Specifications**

#### **PRODUCT NAME**

HP Elite Dragonfly G2 Notebook PC

#### **OPERATING SYSTEM**

**Preinstalled** Windows 10 Pro 64 – HP recommends Windows 10 Pro for business <sup>1</sup>

Windows 10 Pro 64 (National Academic License) <sup>2</sup>

Windows 10 Home 64 1

Windows 10 Home Single Language 64 1

Windows 10 Pro (Windows 10 Enterprise available with a Volume Licensing Agreement) 1

Windows 10 Enterprise 64 (Web Support)1

**FreeDOS** 

- 1. Not all features are available in all editions or versions of Window. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/.
- 2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.1 Not all features are available in all editions or versions of Window. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply, and additional requirements may apply over time for updates. See http://www.windows.com/.

#### **Supported Versions**

HP tested Windows 10, version 1809 on this platform. For testing information on newer versions of Windows 10, please see https://support.hp.com/document/c05195282

#### **PROCESSORS**

Intel® Core™ i7-1185G7 (Up to 4.8 GHz frequency with Intel® Turbo Boost Technology, 12 MB L3 cache, 4 cores), supports Intel® vPro® Technology <sup>3,45,6</sup>

Intel® Core™ i7-1165G7 (Up to 4.7 GHz with Intel® Turbo Boost Technology, 12 MB L3 cache, 4 cores) <sup>3,4 5,6</sup>

Intel® Core™ i5-1145G7 (Up to 4.4 GHz frequency with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores), supports Intel® vPro® Technology <sup>3,45,6</sup>

Intel® Core™ i5-1135G7 (Up to 4.2 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores) <sup>3,45,6</sup>

Intel® Core™ i3-1115G4 with Intel® UHD Graphics (Up to 4.1 GHz with Intel® Turbo Boost Technology, 6 MB L3 cache, 2 cores) 3,45,6

#### **Processor Family**

11th Generation Intel® Core™ i7 processor (i7-1185G7, i7-1165G7) <sup>6</sup>

11th Generation Intel® Core™ i5 processor (i5-1145G7, i5-1135G7) <sup>6</sup>

11th Generation Intel® Core™ i3 processor (i3-1115G4) 6



## **Technical Specifications**

- 3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
- 4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
- 5. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See www.intel.com/technology/turboboost for more information.
- 6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

#### **CHIPSET**

Chipset is integrated with processor

#### **GRAPHICS**

#### Integrated

Intel® Iris® Xe Graphics7 Intel® UHD Graphics

#### Supports

Support HD Decode, DX12, HDMI 2.08

- 7. Intel® Iris® Xe Graphics capabilities require system to be configured with Intel® Core™ i5 or i7 processors and dual channel memory. Intel® Iris® Xe Graphics with Intel® Core™ i5 or 7 processors and single channel memory will only function as UHD graphics.
- 8. HDMI cable sold separately.

#### **DISPLAY**

#### Touch

33.8 cm (13.3") diagonal FHD bent, BrightView WLED UWVA eDP 1.4+PSR2, 400 nits, 72 NTSC, Touch, Low Power (1920x1080)<sup>9,10,11</sup>

33.8 cm (13.3") diagonal UHD bent, HDR-400, BrightView WLED UWVA eDP 1.4+PSR2, 550 nits, 95%sRGB, Touch, (3840x2160)<sup>9,10,11</sup>

- 33.8 cm (13.3") diagonal FHD bent, BrightView WLED UMA eDP 1.4+PSR, 1000 nits, 72% NTSC, Touch with HP Sure View Reflect integrated privacy screen (1920 x 1080) 9,10,11,12
- 9. FHD/HD content required to view FHD/HD images.
- 10. Resolutions are dependent upon monitor capability, and resolution and color depth settings.
- 11. Actual brightness will be lower with touchscreen or Sure View.
- 12. HP Sure View integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.



## **Technical Specifications**

#### STORAGE AND DRIVES

#### **Primary M.2 Storage**

```
2 TB PCIe® Gen3x4 NVMe™ M.2 SSD TLC <sup>13</sup>

1 TB PCIe® Gen3x4 NVMe™ M.2 SSD TLC <sup>13</sup>

512 GB PCIe® Gen3x4 NVMe™ M.2 SSD TLC <sup>13</sup>

256 GB PCIe® Gen3x4 NVMe™ M.2 SSD TLC <sup>13</sup>

128 GB PCIe® Gen3x4 NVMe™ M.2 SSD TLC <sup>13</sup>

512 GB PCIe® NVMe™ Value M.2 SSD <sup>13</sup>

256 GB PCIe® NVMe™ Value M.2 SSD <sup>13</sup>

512 GB PCIe® Gen3x4 NVMe™ M.2 SSD <sup>13</sup>

512 GB PCIe® Gen3x4 NVMe™ M.2 SSD TLC <sup>13</sup>

512 GB PCIe® Gen3x4 NVMe™ M.2 SED SSD TLC <sup>13</sup>

512 GB PCIe® Gen3x4 NVMe™ M.2 SED SSD TLC <sup>13</sup>

512 GB Intel® PCIe® NVMe™ M.2 SED SSD TLC <sup>13</sup>
```

13. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

14. Intel® Optane™ H10 memory system acceleration does not replace or increase the DRAM in your system. Requires 8th Gen or higher Intel® Core™ processor, BIOS version with Intel® Optane™ supported, Windows 10 64-bit, and an Intel® Rapid Storage Technology (Intel® RST) driver.

#### **MEMORY**

#### **Maximum Memory**

32 GB LPDDR4X-4266 SDRAM 15

#### Memory

32 GB LPDDR4X-4266 SDRAM <sup>15</sup> 16 GB LPDDR4X-4266 SDRAM <sup>15</sup> 8 GB LPDDR4X-4266 SDRAM <sup>15</sup>

#### **Memory Slots**

LPDDR4X, system runs at 4266 Supports Dual Channel Memory

15. All slots are non-accessible / non-upgradeable.



## **Technical Specifications**

#### **NETWORKING/COMMUNICATIONS**

#### WLAN

Intel® Dual Band Wi-Fi® 6 AX201 802.11a/b/g/n/ac/ax (2x2) WLAN and Bluetooth® 5 Combo, vPro® 16 Intel® Dual Band Wi-Fi® 6 AX201 802.11a/b/g/n/ac/ax (2x2) WLAN and Bluetooth® 5 Combo, non-vPro® 16

#### **WWAN**

Intel® XMM™ 7360 LTE-Advanced Cat 9 <sup>18</sup>
Qualcomm® Snapdragon™ X55 5G LTE Cat 20 <sup>19</sup>

#### Miracast

Native Miracast Support 20

16. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices.

18. WWAN module is an optional feature, requires factory configuration and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. LTE not available on all products, in all regions.

19. 5G module is an optional feature that must be configured at purchase. AT&T and T-Mobile networks supported in the U.S. Module designed for 5G networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity (ENDC) with both 100Mhz of 5G NR and LTE channel bandwidth, using 256QAM 4x4 as defined by 3GPP, requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. 5G not available on all products, in all regions. Backwards compatible to 4G LTE and 3G HSPA technologies. 5G module planned to be available in select countries, where carrier supported.

20. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.

#### **AUDIO/MULTIMEDIA**

#### Audio

Audio by Bang & Olufsen Microphone/Headphone Combo Audio Jack

#### Camera

720p HD+IR camera with integrated electronic privacy shutter, HP Sure Shutter <sup>21,22</sup> Note: The on/off button for this shutter is located on the function row of the keyboard.

#### Sensors

Accelerometer
Magnetometer
Gyroscope
Ambient light sensor
Hall sensor

- 21. HD content required to view HD images.
- 22. Sold separately or as an optional feature.

#### **KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS**



## **Technical Specifications**

#### Keyboard

HP Modernized Keyboard, spill resistant, Backlit Backlit, Spill-resistant, with HP Dura Keys

#### **Pointing Device**

Glass Clickpad

Microsoft Precision Touchpad Default Gestures Support

#### **Function Keys**

F1 - Display Switching

F2 - Blank or Privacy

F3 - Brightness Down

F4 - Brightness Up

F5 - Audio Mute

F6 - Volume Down

F7 - Volume Up

F8 - Mic Mute

**Backlit Toggle** 

F10 - Insert

F11 - Airplane Mode

F12 - HP Command Center (Programmable Key)

Num Lock

**HP Sure Shutter** 

**Print Screen** 

Delete

#### **SOFTWARE AND SECURITY**

#### **Preinstalled Software**

#### **BIOS**

HP BIOSphere Gen6 23

**HP Drive Lock & Automatic Drive Lock** 

**BIOS Update via Network** 

HP Secure Erase 24

Absolute Persistence Module 25

**HP LAN-Wireless Protection** 

USB enable/disable (via BIOS)

#### **Software**

HP Connection Optimizer 26

**HP Hotkey Support** 

myHP

HP Support Assistant 27

HP QuickDrop<sup>17</sup>

**HP Noise Cancellation Software** 

Touchpoint Customizer for Commercial

**HP Notifications** 

**HP Privacy Settings** 



### **Technical Specifications**

**HP Wireless Button Driver HP Power Manager HP WorkWell** Tile App<sup>28</sup> **HP PC Hardware Diagnostics Windows** Buy Microsoft Office (sold separately) Microsoft Defender 29 HP Smart Support 52

#### **Manageability Features**

HP Driver Packs (download) 30 HP Manageability Integration Kit Gen4 (download) 31 **HP Client Catalog (download)** HP Client Management Script Library (download) HP Image Assistant (download)

#### **Security Management**

Secured-core PC capable 50

**HP Fingerprint Sensor** HP Pro Security Edition (Select models) 32 HP Sure Click 33 HP Sure Sense 34 HP Sure Start Gen6 35 HP Sure Admin 36 HP Sure Recover Gen4 37 HP Sure Run Gen4 38 HP Client Security Manager Gen7 39

TPM 2.0 Embedded Security Chip (Common Criteria EAL4+ Certified) (FIPS 140-2 Level 2 Certified)

- 17. HP Quick Drop requires Internet access and Windows 10 PC preinstalled with HP QuickDrop app and either an Android device (phone or tablet) running Android 7 or higher with the Android HP QuickDrop app, and /or an iOS device (phone or tablet) running iOS 12 or higher with the iOS HP QuickDrop app.
- 23. HP BIOSphere Gen6 is available on select HP Pro and Elite PCs. Features may vary depending on the platform and configurations.
- 24. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
- 25. Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. Certain conditions apply. For full details visit:

https://www.absolute.com/about/legal/agreements/absolute/

- 26. HP Connection Optimizer requires Windows 10.
- 27. HP Support Assistant requires Windows and Internet access.
- 28. Some features require optional subscription to Tile Premium. Tile application for Windows 10 available for download from the Windows Store. Mobile phone app available for download from App Store and Google Play. Requires iOS 11 and greater or Android 6.0 and greater see https://support.thetileapp.com/hc/en-us/articles/200424778 for more information. HP Tile will function as long as the PC has battery power.
- 29. Microsoft Defender Opt in and internet connection required for updates.
- 30. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.



### **Technical Specifications**

31. HP Manageability Integration Kit can be downloaded from

http://www8.hp.com/us/en/ads/clientmanagement/overview.html.

32. HP Pro Security Edition is available preloaded on select HP PCs and includes HP Sure Click Pro and HP Sure Sense Pro. 3-year license required. The HP Pro Security Edition software is licensed under the license terms of the HP End User License Agreement (EULA) that can be found at:

https://h30670.www3.hp.com/ecommerce/common/disclaimer.do#EN\_US as modified by the following: "7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Pro Security Edition (HP Sure Sense Pro and HP Sure Click Pro) is effective upon activation and will continue for thirty-six (36) months thereafter ("Initial Term"). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support." HP Pro Security Edition is optimized for the SMB environment and ships pre-configured - manageability is optional. The HP Pro Security Edition supports a limited tool set that can be used by the HP Manageability Integration Kit which can be downloaded from http://www.hp.com/go/clientmanagement.

- 33. HP Sure Click requires Windows 10 Pro or Enterprise. See https://bit.ly/2PrLT6A SureClick for complete details.
- 34. HP Sure Sense is available on select HP PCs and is not available with Windows10 Home.
- 35. HP Sure Start Gen6 is available on select HP PCs and requires Windows 10.
- 36. HP Sure Admin requires Windows 10, HP BIOS, HP Manageability Integration Kit from

http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.

- 37. HP Sure Recover Gen4 is available on select HP PCs and requires an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data.
- 38. HP Sure Run Gen4 is available on select Windows 10 based HP Pro, Elite and Workstation PCs with select Intel® or AMD processors.
- 39. HP Client Security Manager Gen7 requires Windows and is available on the select HP Elite and Pro PCs.
- 50. Requires an Intel® vPro®, AMD Ryzen™ Pro processor or Qualcomm® processor with SD850 or higher and requires 8 GB or more system memory. Secured-core PC functionality can be enabled from the factory.
- 52. HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Services; or it can be downloaded at: http://www.hp.com/smart-support. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.



### **Technical Specifications**

#### **POWER**

#### **Power Supply**

HP Smart 65 W USB Type-C adapter <sup>40</sup> HP Smart 65 W Slim USB Type-C adapter <sup>40</sup>

#### **Primary Battery**

HP Long Life 2-cell, 38Wh polymer <sup>41,42</sup> HP Long Life 4-cell, 56Wh polymer <sup>41,42</sup> HP Fast Charge Technology (50% in 30 minutes) <sup>43</sup>

#### Battery Life<sup>44</sup>

Up to 16 hours 30 minutes (56 Wh battery)
Up to 11 hours (38 Wh battery)

#### **Battery Weight**

0.57 lb /0.259 kg

- 40. Availability may vary by country.
- 41. Battery is internal and not replaceable by customer. Serviceable by warranty.
- 42. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.
- 43.Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.
- 44. Windows 10 MM18 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See www.bapco.com for additional details.

#### **WEIGHTS & DIMENSIONS**

#### Product Weight 45

Starting at 2.18 lb Starting at 0.98 kg

#### Product Dimensions (w x d x h)

11.98 x 7.78 x 0.63 in 30.43 x 19.75 x 1.61 cm

45. Weight will vary by configuration.



#### **PORTS/SLOTS**

#### **Ports**

2 Thunderbolt™ 4 with USB4 Type-C® 40Gbps signaling rate (USB Power Delivery, DisplayPort™ 1.4)<sup>51</sup>

1 SuperSpeed USB Type-A 5Gbps signaling rate (Charging port)

1 Headphone/microphone combo jack

1 HDMI 2.046

46. HDMI cable sold separately.

51. SuperSpeed USB 20Gbps is not available with Thunderbolt™ 4

#### SERVICE AND SUPPORT

1-year or 3-year limited warranty and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for HP Long Life batteries which will follow the one or three year warranty of the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc. <sup>47</sup>

47. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

#### **CERTIFICATION AND COMPLIANCE**

ENERGY STAR® certified<sup>48</sup>
EPEAT® 2019 Gold in the U.S <sup>49</sup>
TCO 8.0 Certified

48. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit http://www.epeat.net for more information.

49. Configurations of the HP EliteBook x360 1040 G8 Notebook PC that are ENERGY STAR® qualified are identified as HP EliteBook x360 1040 G8 Notebook PC ENERGY STAR on HP websites and on http://www.energystar.gov.



## **Technical Specifications**

#### **SYSTEM UNIT**

Stand-Alone Power Requirements (AC Power)

Nominal Operating 20V, 3.25A

Voltage
Integrated Graphics Intel UMA
Max Operating Power UMA

Shock Non-operating Comply SVTP

Random VibrationNon-operatingComply SVTPOperatingComply SVTP

**Operating** 

Comply SVTP

Altitude (unpressurized) Non-operating Comply SVTP



#### **DISPLAYS**

1. Actual brightness will be lower with touchscreen or Sure View.

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Panel LCD 13.3 inch FHD (1920x1080) BrightView WLED UWVA 72percent cg 400nits eDP 1.4+PSR2 bent LP NWBZ Outline Dimensions (W x H x D) 299.06 x 176.54 mm (max) (FPC folding included)

**Active Area** 293.76 x 165.24 mm (typ.)

Weight 175 g (max)
Diagonal Size 13.3 inch

Thickness 2.0mm / 3.8mm (PCB) (max)

Interface eDP 1.4
Surface Treatment BrightView

**Touch Enabled** Yes

Contrast Ratio1500:1 (typ.)Refresh Rate60 HzBrightness400nits1

Pixel Resolution 1920 x 1080 (FHD)

Format RGB Stripe

Backlight LED

Color Gamut Coverage 72% NTSC (sRGB 100%) (typ.)

Color Depth 8 bit

Viewing Angle UWVA 85/85/85

Panel LCD 13.3 inch UHD (3840x2160) BrightView WLED UWVA HDR-400 sRGB 95percent cg 550nits eDP 1.4+PSR2 bent NWBZ Outline Dimensions (W x H x D) 299.06 x 176.54 mm (max) (FPC folding included)

**Active Area** 293.76 x 165.24 mm (typ.)

Weight 200 g (max)
Diagonal Size 13.3 inch

Thickness 2.0mm / 3.8mm (PCB) (max)

Interface eDP 1.4
Surface Treatment BrightView

Touch Enabled Yes

1400:1 (typ.)

Contrast Ratio 1000:1 (HDR off) (min)

Refresh Rate 60 Hz Brightness 550nits<sup>1</sup>

Pixel Resolution 3840 x 2160 (UHD)

Format RGB Stripe

Backlight LED

Color Gamut CoveragesRGB 95% (min)Color Depth8 bits + 2 FRCViewing AngleUWVA 85/85/85/85



## **Technical Specifications**

Panel LCD 13.3-in FHD (1920 x 1080) BrightView WLED UWVA 72% cg 1000nits eDP 1.4+PSR PrivacyG4 Outline Dimensions (W x H) 299.06 x 176.54 mm (max)

**Active Area** 293.76 x 165.24 mm (typ.)

Weight 220 g (max)

Diagonal Size 13.3 inch

Thickness 3.9 mm (max)

**Interface** eDP 1.4 + PSR (4 lane)

**Surface Treatment** BrightView

**Touch Enabled** Yes

Contrast Ratio 1500:1 (typ.)

**Refresh Rate** 60 Hz **Brightness** 1000 nits<sup>1</sup>

Pixel Resolution 1920 x 1080 (FHD)

Format of LCD Pixel Arrangement RGB

Backlight LED

Color Gamut Coverage 72%

Color Depth 8 bit

Viewing Angle UWVA 85/85/85



## **Technical Specifications**

#### **STORAGE**

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

SSD 128GB 2280 PCIe-3x2 Three Layer Cell Form Factor M.2 2280
Capacity 128 GB
NAND Type TLC

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Weight 0.02 lb (10 g)
Interface PCIe NVMe Gen3X2
Maximum Sequential Read Up To 2047 MB/s
Maximum Sequential Write Up To 1200 MB/s
Logical Blocks 250,069,680

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

SSD 1TB 2280 PCIe-3x4 NVMe Three Layer Cell single-sided

Form Factor M.2 2280
Capacity 1 TB
NAND Type TLC

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Weight 0.02 lb (10 g)
Interface PCIe NVMe Gen3X4
Maximum Sequential Read Up To 2800 MB/s
Maximum Sequential Write Up To 1600 MB/s
Logical Blocks 2,000,409,264

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp] **Features** ATA Security (Option); TRIM; L1.2



### **Technical Specifications**

SSD 256GB 2280 M2 PCIe-3x4 SS NVMe TLC

**Form Factor** M.2 2280 256 GB Capacity TLC **NAND Type** 

0.09 in (2.3 mm) Height Width 0.87 in (22 mm) 0.02 lb (10 q) Weight PCIe NVMe Gen3X4 Interface 2580 MB/s $\sim$  2600 MB/s **Maximum Sequential Read** 900 MB/s $\sim$  1000 MB/s **Maximum Sequential Write** 

500,118,192 **Logical Blocks** 

32° to 158°F (0° to 70°C) [ambient temp] **Operating Temperature** 

ATA Security (Option); TRIM; L1.2 **Features** 

SSD 256GB 2280 PCIe-3x4 NVMe Self **Encrypted OPAL2 Three Layer Cell** 

M.2 2280 **Form Factor** 256 GB Capacity TLC **NAND Type** 

0.09 in (2.3 mm) Height Width 0.87 in (22 mm) 0.02 lb (10 q) Weight PCIe NVMe Gen3X4 Interface Up To 3500 MB/s Maximum Sequential Read Up To 2200 MB/s **Maximum Sequential Write** 500,118,192 **Logical Blocks** 

32° to 158°F (0° to 70°C) [ambient temp] **Operating Temperature** ATA Security; TCG OPAL 2.0; DIPM; TRIM; L1.2

**Features** 

SSD 2TB 2280 PCIe-3x4 **NVMe Three Layer Cell** single-sided

**Form Factor** M.2 2280 2 TB Capacity **NAND Type** TI C

Height 0.09 in (2.3 mm) 0.87 in (22 mm) Width Weight 0.02 lb (10 g) Interface PCIe NVMe Gen3X4 **Up To 3000 MB/s Maximum Sequential Read Maximum Sequential Write** Up To 2100 MB/s

**Logical Blocks** 3,907,029,168

32° to 158°F (0° to 70°C) [ambient temp] **Operating Temperature** 

ATA Security; TCG OPAL 2.0; DIPM; TRIM; DEVSLP **Features** 



### **Technical Specifications**

SSD 512GB 2280 M2 PCIe-3x4 SS NVMe TLC Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

**Logical Blocks** 1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]
Features ATA Security (Option); TRIM; L1.2

SSD 512GB 2280 PCIe-3x4 NVMe Self Encrypted OPAL2 Three Layer Cell Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

**Logical Blocks** 1,000,215,215

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security (Option); TCG Opal 2.0; TRIM; L1.2

SSD 512GB 2280 PCIe NVMe Value Form Factor M.2 2280
Capacity 512GB
NAND Type QLC/TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe

Maximum Sequential ReadUp To 1700 MB/sMaximum Sequential WriteUp To 1500 MB/sLogical Blocks1,000,215,215

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

**Features** ATA Security; TRIM; L1.2

## **Technical Specifications**

SSD 256GB 2280 PCIe NVMe Value Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe

Maximum Sequential ReadUp To 1700 MB/sMaximum Sequential WriteUp to 1300 MB/sLogical Blocks500,118,192

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security, TRIM; L1.2

512GB 2280 PCIe-3x2x2 NVMe+SSD 32GB 3D Xpoint Form Factor M.2 2280 Capacity 512 GB

 NAND Type
 QLC+3D Xpoint

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

InterfacePCIe NVMe Gen3X2X2Maximum Sequential ReadUp To 2400 MB/sMaximum Sequential WriteUp To 1300 MB/sLogical Blocks1,000,215,215

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security, TRIM; L1.2



### **Technical Specifications**

#### **NETWORKING/COMMUNICATIONS**

Intel® Wi-Fi 61 AX20¹ and Wireless LAN Standards Bluetooth® 5.0 802.11ax (2x2) supporting gigabit data rate⁵ (vPro®)

IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac
IEEE 802.11ax
IEEE 802.11d
IEEE 802.11e
IEEE 802.11h
IEEE 802.11i
IEEE 802.11i
IEEE 802.11r
IEEE 802.11r

IEEE 802.11a

Interoperability

Features Wi-Fi 6 technology

**Frequency Band** 

•2.402 – 2.482 GHz 802.11a/n/ac/ax

802.11b/g/n/ax

•4.9 – 4.95 GHz (Japan)

•5.15 – 5.25 GHz •5.25 – 5.35 GHz •5.47 – 5.725 GHz •5.825 – 5.850 GHz

**Data Rates** 

•802.11b: 1, 2, 5.5, 11 Mbps

•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

•802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

• 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

**Modulation** Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

, 1024QAM

Security<sup>3</sup>

•IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only

•AES-CCMP: 128 bit in hardware

•802.1x authentication

•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certificationWPA3 certification



### **Technical Specifications**

•IEEE 802.11i

•WAPI

**Network Architecture** 

Models

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

**Roaming** IEEE 802.11 compliant roaming between access points

Output Power<sup>2</sup> • 802.11b: +18.5dBm minimum

802.11g: +17.5dBm minimum802.11a: +18.5dBm minimum

802.11n HT20(2.4GHz): +15.5dBm minimum
802.11n HT40(2.4GHz): +14.5dBm minimum
802.11n HT20(5GHz): +15.5dBm minimum
802.11n HT40(5GHz): +14.5dBm minimum
802.11ac VHT80(5GHz): +11.5dBm minimum
802.11ac VHT160(5GHz): +11.5dBm minimum
802.11ax HT40(2.4GHz): +10dBm minimum
802.11ax VHT160(5GHz): +10dBm minimum

Power Consumption • Transmit mode: 2.0 W

•Receive mode:1.6 W

Idle mode (PSP)180 mW (WLAN Associated)
 Idle mode:50 mW (WLAN unassociated)
 Connected Standby/Modern Standby: 10mW

•Radio disabled: 8 mW

**Power Management** ACPI and PCI Express compliant power management

802.11 compliant power saving mode

**Receiver Sensitivity<sup>4</sup>** •802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum
802.11a/g, 6Mbps: -86dBm maximum
802.11a/g, 54Mbps: -72dBm maximum
802.11n, MCS07: -67dBm maximum

802.11n, MCS15: -64dBm maximum
802.11ac, MCS0: -84dBm maximum
802.11ac, MCS9: -59dBm maximum

•802.11ax, MCS11(HT40): -59dBm maximum •802.11ax, MCS11(VHT160): -58.5dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard with CNVi Interface

**Dimensions** 1. Type 2230: 2.3 x 22.0 x 30.0 mm



## **Technical Specifications**

2. Type 1216: 1.67 x 12.0 x 16.0 mm

**Weight** 1. Type 2230: 2.8g

2. Type 126: 1.3g

Operating Voltage 3.3v +/- 9%

**Temperature Operating** 14° to 158° F (-10° to 70° C)

**Non-operating**  $-40^{\circ}$  to  $176^{\circ}$  F ( $-40^{\circ}$  to  $80^{\circ}$  C)

**Humidity Operating** 10% to 90% (non-condensing)

**Non-operating** 5% to 95% (non-condensing)

**Altitude Operating** 0 to 10,000 ft (3,048 m)

**Non-operating** 0 to 50,000 ft (15,240 m)

**LED Activity** LED Amber – Radio OFF; LED White – Radio ON

#### HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2/5.0/5.1 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available

Channels

Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)

**Signaling Data Rate** Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps

BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

**Transmit Power** The Bluetooth component shall operate as a Class II Bluetooth device with

a maximum transmit power of + 9.5 dBm for BR and EDR.

**Power Consumption** Peak (Tx): 330 mW

Peak (Rx): 230 mW

Selective Suspend: 17 mW

**Bluetooth Software** 

Supported

Microsoft Windows Bluetooth Software

**Power Management** Microsoft Windows ACPI, and USB Bus Support

Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

**Power Management** 

Certifications

ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL, CSA, and CE Mark

**Bluetooth Profiles** 

Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping

LE Dual Mode LE Link Layer



### **Technical Specifications**

LE Low Duty Cycle Directed Advertising

LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full

LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2

Headset Profile (HSP)

Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

Security & Manageability Intel® vPro™ support with appropriate Intel® chipset components

- 1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported.
- 2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 3. Check latest software/driver release for updates on supported security features.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
- 5. Wi-Fi 5 or 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

Intel® Wi-Fi 61 AX201 and Wireless LAN Standards IEEE 802.11a Bluetooth® 5.0 802.11ax IEEE 802.11b (2x2), supporting gigabit IEEE 802.11q data rate⁵ IEEE 802.11n (non-vPro®) IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v Interoperability

Features Wi-Fi 6 technology



### **Technical Specifications**

**Frequency Band** 802.11b/g/n/ax

•2.402 – 2.482 GHz 802.11a/n/ac/ax •4.9 – 4.95 GHz (Japan)

•5.15 – 5.25 GHz •5.25 – 5.35 GHz •5.47 – 5.725 GHz •5.825 – 5.850 GHz

**Data Rates** •802.11b: 1, 2, 5.5, 11 Mbps

•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

•802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

**Modulation** Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM

Security<sup>3</sup> •IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only

•AES-CCMP: 128 bit in hardware

•802.1x authentication

•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certificationWPA3 certificationIEEE 802.11iWAPI

**Network Architecture** 

Models

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

**Roaming** IEEE 802.11 compliant roaming between access points

• 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum

• 802.11a: +18.5dBm minimum

802.11n HT20(2.4GHz): +15.5dBm minimum
802.11n HT40(2.4GHz): +14.5dBm minimum
802.11n HT20(5GHz): +15.5dBm minimum
802.11n HT40(5GHz): +14.5dBm minimum
802.11ac VHT80(5GHz): +11.5dBm minimum

• 802.11ac VHT160(5GHz): +11.5dBm minimum • 802.11ax HT40(2.4GHz): +10dBm minimum

802.11ax VHT160(5GHz): +10dBm minimum"

Power Consumption •Transmit mode 2.0 W

•Receive mode 1.6 W

Idle mode (PSP) 180 mW (WLAN Associated)
 Idle mode50 mW (WLAN unassociated)

•Connected Standby 10mW

•Radio disabled 8 mW

**Power Management** ACPI and PCI Express compliant power management

802.11 compliant power saving mode

**Receiver Sensitivity**<sup>4</sup> •802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum
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802.11a/g, 54Mbps: -72dBm maximum
802.11n, MCS07: -67dBm maximum
802.11n, MCS15: -64dBm maximum
802.11ac, MCS0: -84dBm maximum

802.11ac, MCS9: -59dBm maximum
 802.11ax, MCS11(HT40): -59dBm maximum

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**Weight** 1. Type 2230: 2.8g

2. Type 126: 1.3g

**Operating Voltage** 3.3v +/- 9%

**Temperature** Operating 14° to 158° F (-10° to 70° C)

**Non-operating**  $-40^{\circ}$  to  $176^{\circ}$  F ( $-40^{\circ}$  to  $80^{\circ}$  C)

**Humidity Operating** 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)"

**Altitude Operating** 0 to 10,000 ft (3,048 m)

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Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

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asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

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a maximum transmit power of + 9.5 dBm for BR and EDR.

**Power Consumption** Peak (Tx): 330 mW

Peak (Rx): 230 mW

Selective Suspend: 17 mW

**Bluetooth Software** 

Supported

Microsoft Windows Bluetooth Software

**Power Management** Microsoft Windows ACPI, and USB Bus Support

Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management Certifications

ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode

LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

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LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel



- 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
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- 5. Wi-Fi 5 or 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

Qualcomm® Snapdragon™ X55 5G Modem (5G + LTE CAT 20) ¹

Technology/Operating bands

WCDMA/HSDPA/HSUPA/HSPA+ operating bands:

Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL)

Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL)

Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL)

Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL)

Band 6: 830 to 840 MHz (UL), 875 to 885 MHz (DL)

Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL)

Band 9: 1750 to 1785 MHz(UL), 1845to 1880 MHz (DL)

Band 19: 830 to 845 MHz (UL), 875 to 890 MHz (DL)

LTE FDD/TDD operating bands:

Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL)

Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL)

Band 3: 1710 to 1785 MHz (UL), 1805 to 1880 MHz (DL)

Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL)

Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL)

Band 7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL)

Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL)

Band 12: 699 to 716 MHz (UL), 729 to 746 MHz (DL)

Band 13: 777 to 787 MHz (UL), 746 to 756 MHz (DL)

Band 14: 788 to 798 MHz (UL), 758 to 768 MHz (DL)

Band 17: 704 to 716 MHz (UL), 734 to 746 MHz (DL)

Band 18: 815 to 830 MHz (UL), 860 to 875 MHz (DL)

Band 19: 830 to 845 MHz (UL), 875 to 890 MHz (DL)

Band 20: 832 to 862 MHz (UL), 791 to 821 MHz (DL)

Band 25: 1850 to 1915 MHz (UL), 1930 to 1995 MHz (DL)

Band 26: 814 to 849 MHz (UL), 859 to 894 MHz (DL)

Band 28: 703 to 748 MHz (UL), 758 to 803 MHz (DL)

Band 29: 717 to 728 MHz (DL)

Band 30: 2305 to 2315 MHz (UL) 2350 to 2360 MHz (DL)

Band 32: 1452 to 1496 MHz (DL)

Band 34: 2010 to 2025 MHz (UL/DL)

Band 38: 2570 to 2620 MHz (UL/DL)

Band 39: 1880 to 1920 MHz (UL/DL)

Band 40: 2300 to 2400 MHz (UL/DL)

Band 41: 2496 to 2690 MHz (UL/DL)

Band 42: 3400 to 3600 MHZ (UL/DL)

Band 46: 5150 to 5925 MHZ (DL)

Band 48: 3550 to 3700 MHZ (UL/DL)

Band 66: 1710 to 1800 MHz (UL), 2110 to 2200 MHz (DL)

Band 71: 663 to 698 MHz (UL), 617 to 652 MHz (DL)

5GNR Sub 6GHZ

n1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL) n2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL) n3: 1710 to 1785 MHz (UL), 1805 to 1880 MHz (DL) n5: 824 to 849 MHz (UL), 869 to 894 MHz (DL) n7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL) n8: 880 to 915 MHz (UL), 925 to 960 MHz (DL) n12: 699 to 716 MHz (UL), 729 to 746 MHz (DL) n20: 832 to 862 MHz (UL), 791 to 821 MHz (DL) n28: 703 to 748 MHz (UL), 758 to 803 MHz (DL)

n41: 2496 to 2690 MHz (UL/DL)

n66: 1710 to 1800 MHz (UL), 2110 to 2200 MHz (DL) n71: 663 to 698 MHz (UL), 617 to 652 MHz (DL)

n77: 3300 to 4200 MHz (UL/DL) n78: 3300 to 3800 MHz (UL/DL) n79: 4400 to 5000 MHz (UL/DL)

Wireless protocol standards

**5GNR Air Interface** 

l 3GPP Rel15 5G NR sub-6

LTE Rel14

20 layers and 2 Gbps downlink (DL) throughput - 4 × 4 MIMO across 5x CA

200 Mbps uplink (UL) throughput - 40 MHz ULCA and 256 QAM

**WCDMA** 

R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-A, MS-B)

**GPS bands** GPS: L1 (1575.42MHz); L5 (1176MHz)

GLONASS: L1 (1602MHz) BeidouB1(1561.098MHz)

Galileo E1 (1575.42); E5a (1176MHz)

Maximum data rates 5G sub 6G: 3.8 Gbps

LTE: ue-CategoryDL 20, (DL: 2 Gbps) ue-CategoryUL 13, (UL: 150Mbps)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)

**Maximum output** 

power

LTE: 23 dBm in all band except B41

LTE B41 HPUE = 26dBm

HSPA+: 23.5 dBm

Maximum power 5G Sub 6 : 2500 mA

LTE: 1,300 mA (peak); 1100 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 8 q

Dimensions 42 mm × 30 mm × 2.6 mm (Length x Width x

Thickness)

consumption

1. 5G module is an optional feature that must be configured at purchase. AT&T and T-Mobile networks supported in the U.S. Module designed for 5G networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity (ENDC) with both 100Mhz of 5G NR and LTE channel bandwidth, using 256QAM 4x4 as defined by 3GPP, requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. 5G not available on all products, in all regions. Backwards compatible to 4G LTE and 3G HSPA technologies. 5G module planned to be available in select countries, where carrier supported.

Intel® XMM™ 7360 LTE-Advanced 1

Technology/Operating bands

FDD LTE:

LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700 (Band 4),

850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12),

700 (Band 13)

700 (Band 17), 850 (Band 18), 850 (Band 19), 800 (Band 20), 1450 (Band

21), 850 (Band 26)

700 (Band 28) MHz, 700 (Band 29), 2300 (Band 30), 2100 (Band 66) MHz

TDD LTE:

2600 (Band 38), 1900 (Band 39), 2300 (Band 40), 2500 (Band 41) MHz HSPA+: 2100 (Band 1), 1900 (Band 2), 1700 (Band 4), 850 (Band 5), 900

(Band 8) MHz

Wireless protocol

standards

3GPP Release 11 LTE Specification CAT.9, MAX 60MHz aggregation BW

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

**GPS** Standalone, A-GPS (MS-B and LTO)

**GPS** bands GPS 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou

1561.098 ± 2.046 MHz

Maximum data rates LTE: 450 Mbps (DL 3CA), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload)

HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)

Maximum output power LTE: 23 dBm

HSPA+: 23.5 dBm

**Maximum power** LTE: 1,200 mA (peak); 900 mA (average) consumption HSPA+: 1,100 mA (peak); 800 mA (average)

**Form Factor** M.2, 3042-S3 Key B

Weight 6 q

**Dimensions** 

(Length x Width x

Thickness)

42 x 30 x 2.3 mm

1. WWAN module is an optional feature, requires factory configuration and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. LTE not available on all products, in all regions.



### **Technical Specifications**

#### **POWER**

AC Adapter 65 Watt nPFC Slim USB type C Straight 1.0m

**Dimensions** 88x53.5x21mm Weiaht Input

unit: 220g +/- 10g 100 to 240 VAC

**Input Efficiency** 

81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A

Input frequency range

47 ~ 63 Hz

**Input AC current** 

1.6 A at 90 VAC and maximum load

**Output power** 65W

> **DC** output 5V/9V/12V/15V/20V Hold-up time 5ms at 115 Vac input

> > <8.0A

**Output current limit** 

Connector USB Type-C

**Environmental Design** Operating temperature

32°Fto 95°F (0°to 35°C) Non-operating (storage) -4°Fto 185°F (-20°to 85°C)

temperature

**Altitude** 0 to 16,400 ft (0 to 5000m)

**Humidity** 5% to 95% **Storage Humidity** 5% to 95%

**EMI and Safety** Certifications

Output

Eq:

\*CE Mark - full compliance with LVD and EMC directives

\* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

\* MTBF - over 100,000 hours at 25°C ambient condition.

AC Adapter 65 Watt nPFC Dimensions Standard USB type C Straight 1.0m

90.0x51x28.5mm

Weight unit: 250g +/- 10g Input 100 to 240 VAC

> **Input Efficiency** 81.5% min at 115 Vac/ 230Vac @ 5V/3A

86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A

Input frequency range

**Input AC current** 1.6 A at 90 VAC and maximum load

47 ~ 63 Hz

Output **Output power** 65 W

> **DC** output 5V/9V/12V/15V/20V Hold-up time 5ms at 115 Vac input

**Output current limit** 8.0A Max.

Connector **USB TYPE C** 

**Environmental Design** Operating temperature 32°F to 95°F (0°to 35°C)

Non-operating (storage) -4°F to 185°F (-20°to 85°C)

temperature

**Altitude** 0 to 16,400 ft (0 to 5000m)

**Humidity** 20% to 95% **Storage Humidity** 10% to 95%

**Safety Certifications** - CE Mark - full compliance with LVD and EMC directives

> - Worldwide safety standards -IEC60950, EN60950, UL60950, UL62368, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022

Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. - MTBF - over 200.000 hours at 25°C ambient condition.

HP 4-cell Long Life Li-Ion(56Wh)

**Dimensions**  $(H \times W \times L)$ 

5.25x85.00x274.00 mm

Weight  $0.259 \, kg$ 

Cells/Type 4cell Lithium-Ion Polymer cell / 446872 Energy Voltage 8.8V/7.7V

**Amp-hour capacity** 7.3Ah/7.0Ah **Watt-hour capacity** 56 Wh

Operating (Charging) 32° to 113° F (0° to 45° C)

Operating (Discharging) 14° to 122° F (-10° to 60° C)

**Optional Travel** 

**Temperature** 

No

**Battery Available** 

HP 2-cell Long Life Li-Ion(38Wh)

**Dimensions**  $(H \times W \times L)$ 5.20\*79.40\*274.00

Weight  $0.16 \, kg$ 

2cell Lithium-Ion Polymer cell / 4453C2 Cells/Type Energy Voltage 8.8V/7.7V **Amp-hour capacity** 4.93Ah/4.68Ah

> 38 Wh **Watt-hour capacity**

Operating (Charging) 32° to 113° F (0° to 45° C) **Temperature** 

Operating (Discharging) 14° to 122° F (-10° to 60° C)

**Optional Travel Battery** 

Available

No

### **Technical Specifications**

#### **FINGERPRINT READER**

**Model:** Model: Synaptics Validity VFS7552 touch sensor

Mobile Voltage Operation: Mobile Voltage Operation: 3.0V to 3.6V

**Operating Temperature:** Operating Temperature: 14° – 167°F (-10°-75°C)

**Current Consumption Image:** Current Consumption Image: 36mA peak **Low Latency Wait For Finger:** Low Latency Wait For Finger: 950 uA

Capture Rate: Capture Rate: 30 cm/sec

**ESD Resistance:** ESD Resistance: IEC 61000-4-2 4B (+15KV)

**Detection Matrix:** Detection Matrix: 200\*1 (Plus another secondary line) / 508 dpi / 10mm sensor area

FRR (False Reject Rate) / FAR

(False Acceptance Rate):

FRR (False Reject Rate) / FAR (False Acceptance Rate): FRR ~ 1% @ 1:50K FAR

#### ENVIRONMENTAL DATA

## Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- US Federal Energy Management Program (FEMP)
- EPEAT<sup>®</sup> Gold registered in the United States. See http://www.epeat.net for registration status in your country.
- TCO 8.0
- China Energy Conservation Program (CECP)
- China State Environmental Protection Administration (SEPA)
- Taiwan Green Mark
- Korea Eco-label
- Japan PC Green label\*

## Sustainable Impact Specifications

- Ocean-Bound Plastic in speaker enclosure and bezel1
- 10% post-consumer recycled plastic<sup>2</sup>
- Low halogen<sup>3</sup>
- Outside Box and corrugated cushions are 100% sustainably sourced and recyclable<sup>4</sup>
- Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable<sup>5</sup>
- Bulk packaging available
- 1. Percentage of ocean-bound plastic contained in each component varies by product
- 2. Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.
- 3. External power supplies, WWAN modules, power cords, cables and peripherals excluded.
- 4. 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.
- 5. Fiber cushions made from 100% recycled wood fiber and organic materials.



## **Technical Specifications**

System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the				
	Notebook model is based on a "Typically Configured Notebook".				
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 5	0Hz	100VAC, 50Hz	
Normal Operation	5.07 W	5.26 W		4.92 W	
(Sort idle)					
Normal Operation	0.73 W	0.82 W		0.78 W	
(Long idle)					
Sleep	0.73 W	0.82 W		0.78 W	
Off	0.30 W	0.32 W		0.29 W	
	family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.				
Heat Dissipation*	115VAC, 60Hz	230VAC, 5	0Hz	100VAC, 50Hz	
Normal Operation (Short idle)	16 BTU/hr	16 BTU/i	nr	16 BTU/hr	
Normal Operation	3 BTU/hr	3 BTU/h	r	2 BTU/hr	
(Long idle)					
Sleep	3 BTU/hr	3 BTU/hr		2 BTU/hr	
Off	1 BTU/hr 1 BTU/hr 1 BTU/hr				
	*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.				
Declared Noise	Sound Power			Sound Pressure	
Emissions (in accordance with ISO 7779 and ISO 9296)	(L <sub>WAd</sub> , bels)		(L <sub>pAm</sub> , decibels)		
Typically Configured – Idle	2.7		13.8		
Fixed Disk – Random	3.0		19.8		
writes				13.0	



## **Technical Specifications**

<b>Longevity and Upgrading</b>	This product can be upgraded, possibly extending its useful life by several years. Upgradeable					
	features and/or components contained in the Spare parts are available throughout the w					
	period and o	period and or for up to "5" years after the end of production.				
Additional Information	<ul> <li>This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.</li> <li>This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC.</li> <li>This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).</li> <li>This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net</li> <li>Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and</li> </ul>					
		1043. s product is 11.07% recycle-able when properly	disposed of at end of life.			
Packaging Materials	External:	PAPER/Corrugated	215 g			
		PAPER/Corrugated	49 g			
	Internal:	PLASTIC/polypropylene	3 g			
		PLASTIC/Polyethylene low density	111 g			
		PAPER/Molded pulp	102 g			
		PAPER/Molded pulp	154 g			
	The plastic packaging material contains at least 0% recycled content.  The corrugated paper packaging materials contains at least 64% recycled content.					
RoHS Compliance	HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.  We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.  We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.  To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.					
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at:  http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html  • Asbestos  • Certain Azo Colorants  • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics					



## **Technical Specifications**

<ul> <li>Chlorinated Hydrocarbo</li> </ul>
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- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

#### **Packaging Usage**

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

## End-of-life Management and Recycling

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: <a href="http://www.hp.com/go/reuse-recycle">http://www.hp.com/go/reuse-recycle</a> or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: <a href="http://www.hp.com/go/recyclers">http://www.hp.com/go/recyclers</a>. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.



## **Technical Specifications**

HP, Inc. Corporate	For more information about HP's commitment to the environment:	
Environmental	Global Citizenship Report	
Information	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html	
	Eco-label certifications	
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html	
	ISO 14001 certificates:	
	http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842	
	and	
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf	

### **COUNTRY OF ORIGIN**

China



## Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part Number
Audio	HP Wired Thunderbolt Audio Module	3AQ21AA,3AQ21UT,3AQ21ET
	HP Wired USB-A UC SPK Phone	4VW02AA
Case	HP Business 13.3 Sleeve	2UW00AA,2UW00UT,2UW00ET
	HP Business 14.1 Sleeve	2UW01A6
	HP Business 14.1 Sleeve	2UW01AA,2UW01UT,2UW01ET
	HP Business 15.6 Case	2SC66A6
	HP Business 15.6 Top Load	2SC66AA,2SC66UT,2SC66ET
	HP Business 17.3 Backpack	2SC67A6
	HP Business 17.3 Backpack	2SC67AA,2SC67UT,2SC67ET
	HP Business Slim 14.1 Top Load	2SC65A6
	HP Business Slim 14.1 Top Load	2SC65AA,2SC65UT,2SC65ET
	HP Business Slim 17.3 Top Load	2UW02A6
	HP Business Slim 17.3 Top Load	2UW02AA,2UW02UT,2UW02ET
	HP Executive 14.1 Tote	6KD10AA,6KD10UT,6KD10ET
	HP Executive 15.6 Backpack	6KD07AA,6KD07UT,6KD07ET
	HP Executive 15.6 Top Load	6KD06AA,6KD06UT,6KD06ET
	HP Executive 17.3 Backpack	6KD05AA,6KD05UT,6KD05A9,6K D05ET
	HP Executive 17.3 Top Load	6KD08AA,6KD08UT,6KD08ET
	HP Executive Convertible 14.1 Tote	5KN27AA
	HP Executive Leather 15.6 Top Load	6KD09AA,6KD09UT,6KD09ET
	HP Executive Slim 14.1 Top Load	6KD04AA,6KD04UT,6KD04ET
	HP Prelude G2 15.6 Backpack	1E7D6A6
	HP Prelude G2 15.6 Backpack	2Z8P3AA,1E7D6AA
	HP Prelude G2 15.6 Top Load	1E7D7A6
	HP Prelude G2 15.6 Top Load	2Z8P4AA,1E7D7AA
	HP Prelude Pro Recycled 15.6 Backpack	1X644A6
	HP Prelude Pro Recycled 15.6 Backpack	1X644AA,1X644UT,1X644ET
	HP Prelude Pro Recycled 15.6 Top Load	1X645A6
	HP Prelude Pro Recycled 15.6 Top Load	1X645AA,1X645UT,1X645ET
	HP Renew Business 14.1 Laptop Bag AMO	3E5F9A6
	HP Renew Business 14.1 Laptop Bag	3E5F9AA,3E5F9UT,3E5F9ET
	HP Renew Business 14.1 Laptop Sleeve	3E2U7AA,3E2U7UT,3E2U7ET
	HP Renew Business 14.1 Sleeve	3E2U7A6
	HP Renew Business 15.6 Laptop Bag	3E5F8A6
	HP Renew Business 15.6 Laptop Bag	3E5F8AA,3E5F8UT,3E5F8ET
	HP Renew Business 17.3 Laptop Backpack	3E2U5A6
	HP Renew Business 17.3 Laptop Backpack	3E2U5AA,3E2U5UT,3E2U5ET



### Options and Accessories (sold separately and availability may vary by country)

HP Renew Business 17.3 Laptop Bag 3E2U6AA,3E2U6UT

Docks HP USB-C/A 120W G2 Universal Dock 5TW13AA, 5TW13ET, 5TW13UT

> HP Thunderbolt 120W G2 Dock 6HP48AA, 2UK37AA, 2UK37ET

> HP Thunderbolt 120W G2 Dock w/Audio **3YE87AA, 3YE87ET**

> HP Thunderbolt 230W G2 Dock 2UK38AA, 2UK38UT, 2UK38ET

> HP Thunderbolt 230W G2 Dock w/Combo Cable 3TR87AA, 3TR87UT, 3TR87ET

> HP USB-C 120W G5 Dock 26D32AA, 5TW10XX

> **HP USB-C Mini Dock** 1PM64AA,1PM64UT, 1PM64ET

> HP USB-C Travel Dock G2 7PJ38AA,7PJ38UT,7PJ38ET

Input/Output **HP WL USB Agnes Keyboard T6U20AA, T6U20UT** 

> HP Collaboration WL Wanda Bluetooth Kevboard **Z9N39AA. Z9N39UT**

> HP Wired Desktop 320K Keyboard 9SR37AA, 9SR37UT, 9SR37ET

> HP 125 WD USB Keyboard 266C9AA, 266C9UT, 266C9ET HP Wireless Rechargeable 950MK Mouse and Keyboard 3M165AA, 3M165UT

> HP USB Essential Keyboard/Mouse H6L29AA

> HP Wired Desktop 320MK Mouse and Keyboard 9SR36AA, 9SR36UT, 9SR36ET

> **HP Slim Wireless Keyboard and Mouse** T6L04AA, T6L04UT

> HP Wired Desktop 320M Mouse 9VA80AA, 9VA80UT, 9VA80ET

> **HP** Wired Mouse 265A9AA, 265A9UT, 265A9ET

> **HP LSR Wired Mouse** 265D9AA, 265D9UT, 265D9UT

> HP USB 320M Wired Mouse 9VA80AA,9VA80UT,9VA80ET

> **HP Comfort Grip USB Wireless Mouse** H2L63AA, H2L63UT

> HP Bluetooth Fingerprint Reader USB Mouse 4TS44AA,4TS44UT,4TS44ET

> HP Bluetooth Travel Bluetooth Mouse 6SP30AA,6SP30UT,6SP30ET

> HP Creator USB-A+Bluetooth 935 Wireless Mouse Black 1D0K8AA, 1D0K8ET, 1D0K8UT

> HP Presenter Bluetooth 4.2 Bluetooth Mouse 2CE30AA,2CE30UT,2CE30ET

> HP UltraMobile USB-A Wireless Mouse **H6F25AA. H6F25UT**

> **HP USB-A Fingerprint Reader USB Mouse** 4TS44AA, 4TS44UT, 4TS44ET

> HP USB-A Laser 3 Button USB Mouse H4B81AA, H4B81ET

> **HP USB Premium USB Mouse** 1JR32AA,1JR32UT

> **HP USB Premium Wireless Mouse** 1JR31AA,1JR31UT

> **HP USB Travel USB Mouse** G1K28AA, G1K28ET

> HP Multi-Device 635 Black Wireless Mouse

HP USB-A+Bluetooth Travel Bluetooth Mouse 6SP30AA, 6SP30UT, 6SP30ET

**HP HDMI to DVI Adapter** 

**HP HDMI to VGA Adapter** H4F02AA, H4F02UT, H4F02ET

HP USB 3.0 to Gigabit Adapter N7P47AA

HP USB-C to 4.5mm Adapter 4ST73AA



1D0K2AA

## Options and Accessories (sold separately and availability may vary by country)

HP USB-C to HDMI 2.0 Adapter 2PC54AA,1WC36UT,1WC36AA

HP USB-C to RJ45 Adapter V8Y76AA, V7W66AA, V7W66UT

HP USB-C to USB-A Adapter N2Z63AA, N2Z63UT

HP 4.5 mm and USB-C Dock Adapter G2 6LX61AA

HP USB-C to USB-A Hub Jake Z8W90AA, Z6A00XX

HP USB-C to USB-C Cable Blight 5AR72AA

HP USB-C to VGA Adapter P7Z54AA, N9K76AA, N9K76UT

Power HP 45W USB-C G2 Zeus AC Power Adapter 1HE07AA,1HE07UT

HP 45W USB-C LC Dali AC Power Adapter 1MZ01AA

HP 65W USB-C Auto Chevy AC Power Adapter 5TQ76AA,5TQ76UT,5TQ76ET

HP 65W USB-C Hades AC Power Adapter X7W50AA,1HE08XX

HP 65W USB-C LC AC Power Adapter 1P3K6AA

HP 90W USB-C Gaia AC Power Adapter 2LN85AA

HP USB Power Bank N9F71AA, N9F71UT

HP USB-C Essential Power Bank 3TB55AA,3TB55UT

Storage HP USB DVD-Writer EXT ODD Y3T76AA, F2B56AA, F2B56UT,

F2B56ET

Security HP Nano Cable Lock 1AJ39AA,1AJ39UT

HP Sure Key Cable Lock 6UW42AA



## **Summary of Changes**

Date of change:	Version History:		Description of change:
January 22 <sup>,</sup> 2021	V1 to V2		At a Glance section update, WPA3 certification
February 10, 2021	V2 to V3	Add	Environmental Data
February 17, 2021	V3 to V4	Update	Environmental Data
March 2, 2021	V4 to V5	Update	Battery Life
March 5, 2021	V5 to V6	Update	USB ports
March 11, 2021	V6 to V7	Update	Environmental Data
April 16, 2021	V7 to V8	Update	Options and Accessories
April 20, 2021	V8 to V9	Add	Fingerprint Reader
May 6, 2021	V9 to V10	Add	HP Smart Support

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